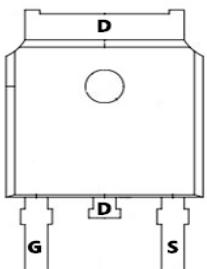
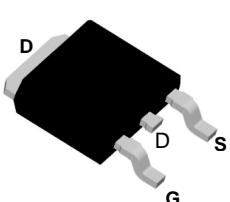
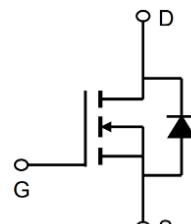


# TM60N02D

## N-Channel Enhancement Mosfet

<b>General Description</b> <ul style="list-style-type: none"> <li>Low <math>R_{DS(ON)}</math></li> <li>RoHS and Halogen-Free Compliant</li> </ul> <b>Applications</b> <ul style="list-style-type: none"> <li>Load switch</li> <li>PWM</li> </ul>	<b>General Features</b> <p> <math>V_{DS} = 20V</math> <math>I_D = 60A</math>  <math>R_{DS(ON)} = 4.9m\Omega</math>(typ.) @ <math>V_{GS} = 4.5V</math>          100% UIS Tested          100% <math>R_g</math> Tested       </p>
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 D:TO-252-3L   Marking: 60N02
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### Absolute Maximum Ratings ( $T_A = 25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_d@T_c=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	60	A
$I_d@T_c=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	35	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	240	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	48	mJ
$I_{AS}$	Avalanche Current	31	A
$P_d@T_c=25^\circ C$	Total Power Dissipation <sup>4</sup>	38	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{JC}$	Thermal Resistance Junction Case <sup>1</sup>		4.2	°C/W

**TM60N02D**
**N-Channel Enhancement Mosfet**
**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	20	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=20\text{V}$ , $V_{\text{GS}}=0\text{V}$ ,	-	-	1.0	$\mu\text{A}$
$I_{\text{GSS}}$	Gate to Body Leakage Current	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=\pm 12\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_D=250\mu\text{A}$	0.4	0.7	1.0	V
$R_{\text{DS}(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{\text{GS}}=4.5\text{V}$ , $I_D=25\text{A}$	-	4.9	6.0	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$ , $I_D=15\text{A}$	-	6.0	7.2	
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=10\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1.0\text{MHz}$	-	1832	-	pF
$C_{\text{oss}}$	Output Capacitance		-	289	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	271	-	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=10\text{V}$ , $I_D=25\text{A}$ , $V_{\text{GS}}=4.5\text{V}$	-	23	-	nC
$Q_{\text{gs}}$	Gate-Source Charge		-	4.5	-	nC
$Q_{\text{gd}}$	Gate-Drain("Miller") Charge		-	7.3	-	nC
<b>Switching Characteristics</b>						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=10\text{V}$ , $I_D=25\text{A}$ , $R_{\text{GEN}}=3\Omega$ , $V_{\text{GS}}=4.5\text{V}$	-	15	-	ns
$t_r$	Turn-on Rise Time		-	37	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	52	-	ns
$t_f$	Turn-off Fall Time		-	21	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	60	A	
$I_{\text{SM}}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	240	A	
$V_{\text{SD}}$	Drain to Source Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=30\text{A}$	-	-	1.2	V
$\text{trr}$	Body Diode Reverse Recovery Time	$\text{IF}=25\text{A}, \text{dl}/\text{dt}=100\text{A}/\mu\text{s}$	-	25	-	ns
$Q_{\text{rr}}$	Body Diode Reverse Recovery Charge		-	21	-	nC

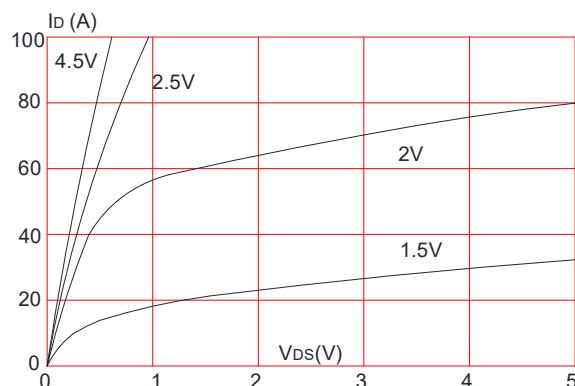
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{\text{DD}}=10\text{V}$ ,  $V_G=4.5\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_G=25\Omega$ ,  $I_{\text{AS}}=13.8\text{A}$

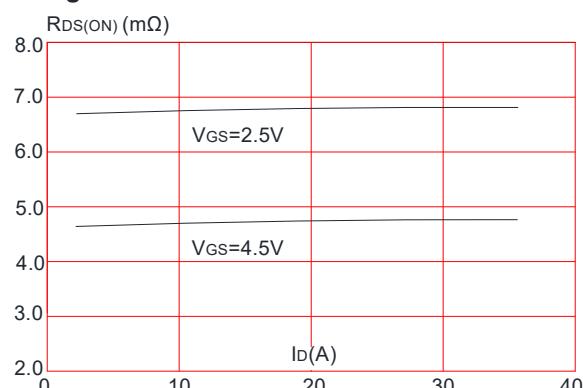
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

## Typical Performance Characteristics

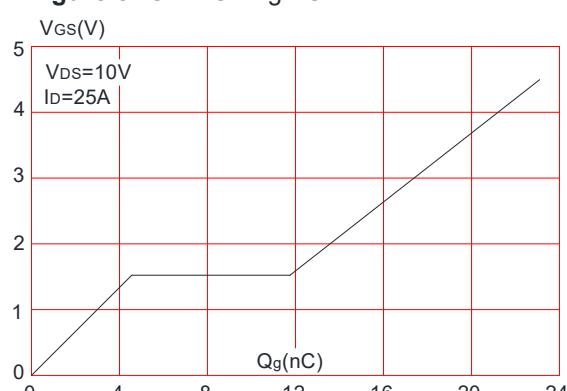
**Figure1:** Output Characteristics



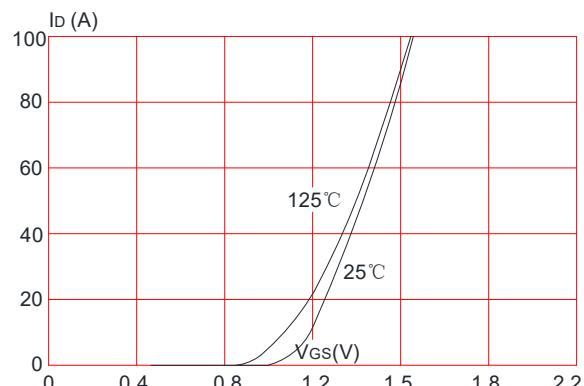
**Figure 3:** On-resistance vs. Drain Current



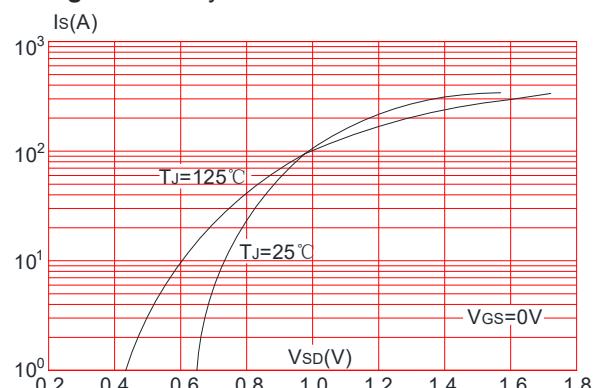
**Figure 5:** Gate Charge Characteristics



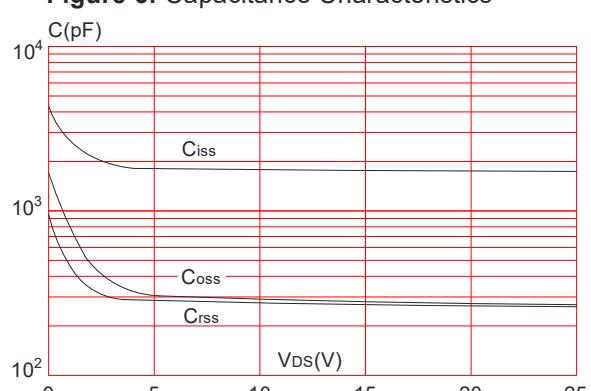
**Figure 2:** Typical Transfer Characteristics



**Figure 4:** Body Diode Characteristics



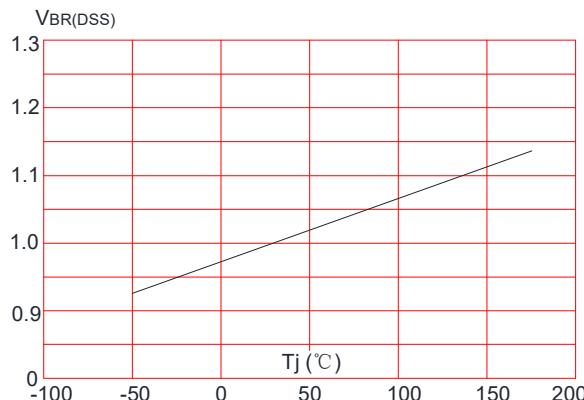
**Figure 6:** Capacitance Characteristics



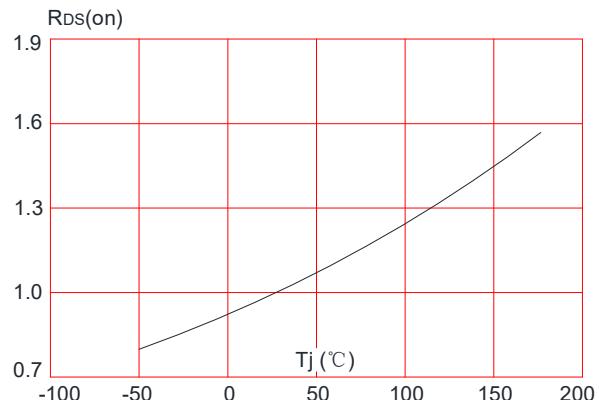
## TM60N02D

## N-Channel Enhancement Mosfet

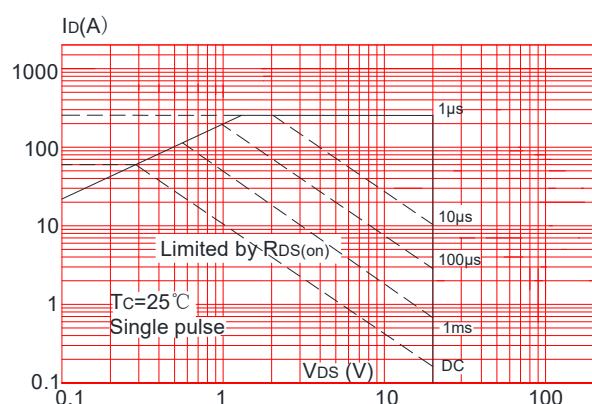
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



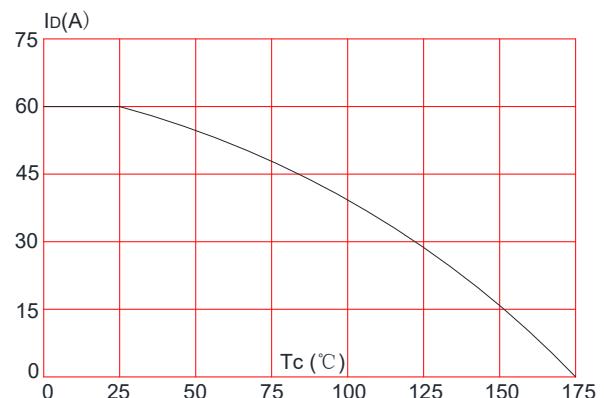
**Figure 8:** Normalized on Resistance vs. Junction Temperature



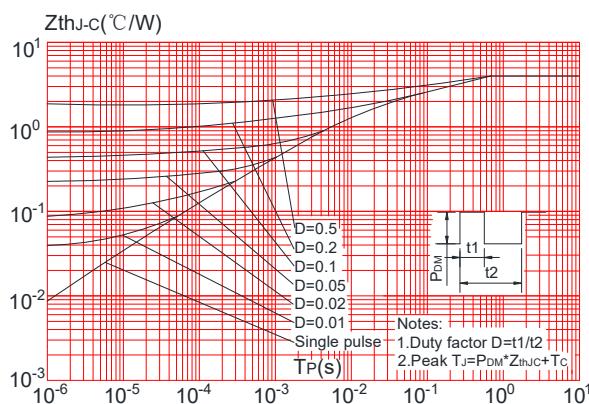
**Figure 9:** Maximum Safe Operating Area



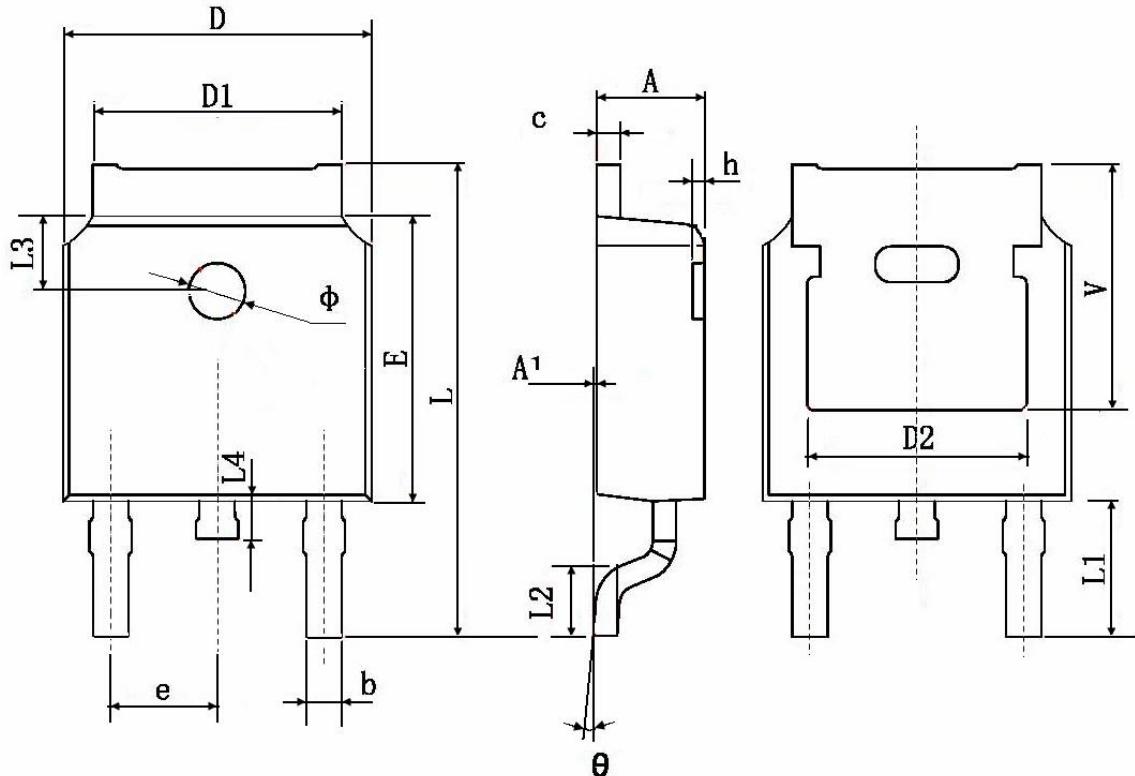
**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



## Package Information: TO-252-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	